

Figure 1

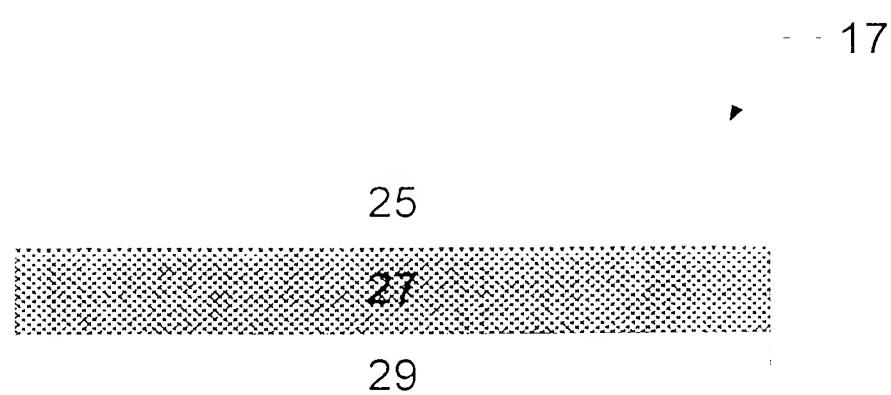


Figure 2

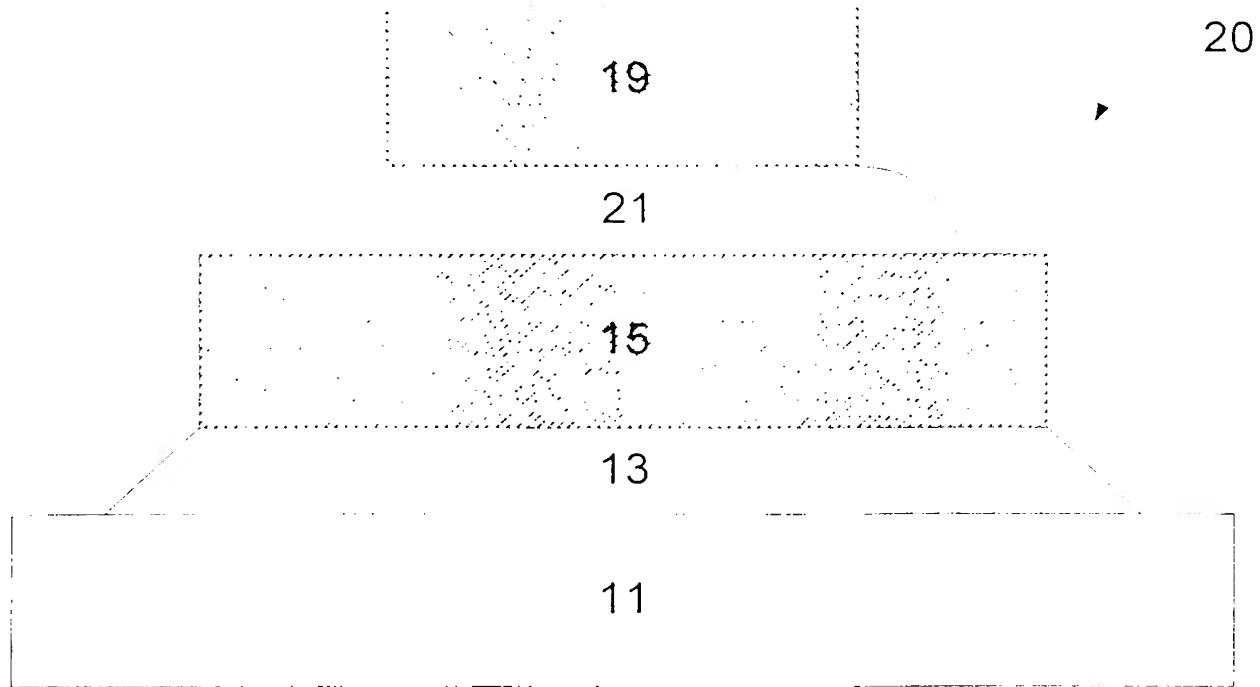
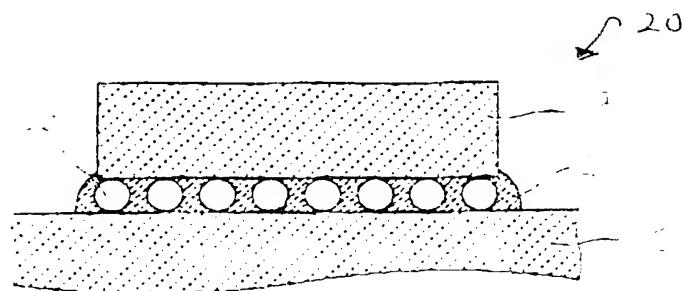


Figure 3



START

- 30

33

Provide a lead frame

35

Attach a first integrated circuit chip to a  
top surface of the lead frame with a  
conductive adhesive

37

Attach a second integrated circuit chip  
to a top surface of the first integrated  
circuit chip with an insulating adhesive  
tape

END

Figure 5

START

40

43

Provide a lead frame

45

Attach a first integrated circuit chip to a  
top surface of the lead frame with a  
conductive adhesive

47

Attach a second integrated circuit chip  
to a top surface of the first integrated  
circuit chip with an insulating epoxy  
adhesive

-NL-

Figure 6